MA4X160 (MA160)

Silicon epitaxial planar type

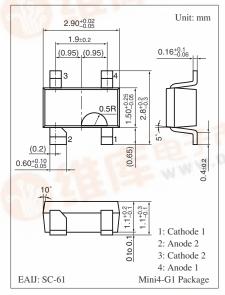
For high-speed switching circuits

■ Features

- Two isolated elements are contained in one package, allowing high-density mounting
- Centrosymmetrical wiring, allowing to free from the taping direction
- Short reverse recovery time t_{rr}
- Small terminal capacitance C_t

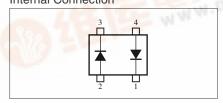
■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter		Symbol	Rating	Unit
Reverse voltage		V _R	40	V
Maximum peak reverse voltage		V_{RM}	40	V
Forward current	Single	I _{F(AV)}	100	mA
(Average)	Double		75	
Repetitive peak	Single	I_{FRM}	225	mA
forward current	Double		170	
Non-repetitive peak	Single	I_{FSM}	500	mA
forward surge current *	Double		375	
Junction temperature		T _j	150	°C
Storage temperature		T_{stg}	-55 to +150	°C
Note) *: t = 1 s			711	C CO.
			WW.DZS	



Marking Symbol: M1D

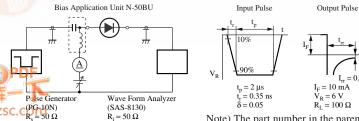
Internal Connection



■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

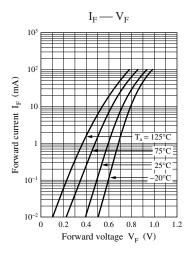
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	$V_{\rm F}$	$I_F = 100 \text{ mA}$		0.95	1.20	V
Reverse voltage	V _R	$I_R = 100 \mu A$	40	Title		V
Reverse current	I_R	$V_R = 35 \text{ V}$			0.1	μΑ
Terminal capacitance	Ct	$V_R = 0 V, f = 1 MHz$	/// EF	0.9	2.0	pF
Reverse recovery time *	t _{rr}	$I_F = 10 \text{ mA}, V_R = 6 \text{ V}$			3	ns
		$I_{rr} = 0.1 I_R$, $R_L = 100 \Omega$				

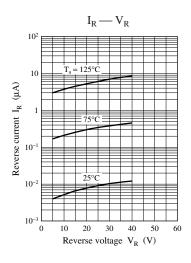
- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring method for diodes.
 - 2. Absolute frequency of input and output is 100 MHz.
 - 3. *: t_{rr} measurement circuit

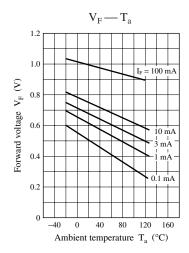


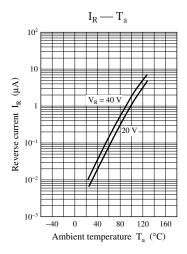
Note) The part number in the parenthesis shows conventional part number.

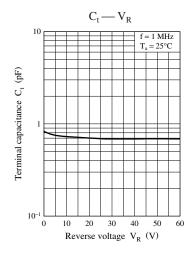
MA4X160 Panasonic

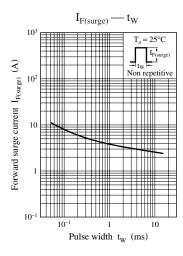












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